



SPECIFICATION

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- Samsung P/N : CL31A475KOHNNNE
- Descriptiont : CAP, 4.7 µF, 16V, ±10%, X5R, 1206

A. Samsung Part Number

			<u>CL</u>	<u>31</u>	<u>A</u>	<u>475</u>	<u>K</u>	<u>o</u>	<u>H</u>	<u>N</u>	<u>N</u>	N	<u>E</u>			
			1	2	3	4	5	6	1	8	9	10	1			
1	Series	Samsun	a Multi	-laver	Cer	amic C	ana	citor								
-	Size		(inch c	•	001		•	± 0.2	2	mm		W:	1.6	± 0.2	mm	
3	Dielectric	X5R					8	Inne	r ele	ctroc	le		Ni			
4	Capacitance	4.7	μF					Tern	nina	tion			Cu			
5	Capacitance	±10	%					Plati	ng				Sn 10	0%	(Pb F	ree)
	tolerance						9	Proc	luct				Norm	al		
6	Rated Voltage	16	V				10	Spe	cial				Rese	rved foi	r future	use
\bigcirc	Thickness	1.6	± 0.2	mm			1	Pacl	kagir	ng			Embo	ssed T	ype, 7"	reel

B. Samsung Reliability Test and Judgement condition

	Performance	Test condition						
Capacitance	Within specified tolerance	1klz±10% 1.0±0.2Vrms						
Tan δ (DF)	0.075 max.							
Insulation	10,000Mohm or 100Mohm·µF	Rated Voltage 60~120 sec.						
Resistance	Whichever is Smaller							
Appearance	No abnormal exterior appearance	Microscope (×10)						
Withstanding	No dielectric breakdown or	250% of the rated voltage						
Voltage	mechanical breakdown							
Temperature	X5R							
characteristics	(From -55 $^{\circ}$ to 85 $^{\circ}$, Capacitance change should be within ±15%)							
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.						
of Termination	terminal electrode							
Bending Strength	Capacitance change : within ±12.5%	Bending to the limit (1mm)						
		with 1.0mm/sec.						
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder						
	is to be soldered newly	245±5℃, 3±0.3sec.						
		(preheating : 80~120 ℃ for 10~30sec.)						
Resistance to	Capacitance change : within ±7.5%	Solder pot : 270±5°C, 10±1sec.						
Soldering heat	Tan δ, IR : initial spec.							

	Performance	Test condition				
Vibration Test	Capacitance change : within ±5%	Amplitude : 1.5mm				
	Tan δ, IR : initial spec.	From 10Hz to 55Hz (return : 1min.)				
		2hours \times 3 direction (x, y, z)				
Moisture	Capacitance change : within ±12.5%	With rated voltage				
Resistance	Tan δ : 0.1 max	40±2℃, 90~95%RH, 500+12/-0hrs				
	IR : 500Mohm or 25Mohm $\cdot \mu F$					
	Whichever is Smaller					
High Temperature	Capacitance change : within ±12.5%	With 200% of the rated voltage				
Resistance	Tan δ : 0.1 max	Max. operating temperature				
	IR : 1000Mohm or 50Mohm · μF					
	Whichever is Smaller	1000+48/-0hrs				
Temperature	Capacitance change : within ±7.5%	1 cycle condition				
Cycling	Tan δ, IR : initial spec.	Min. operating temperature \rightarrow 25 °C				
		\rightarrow Max. operating temperature \rightarrow 25 °C				
		5 cycle test				

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5°C, 10sec. Max)

* For the more detail Specification, Please refer to the Samsung MLCC catalogue.